



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPD031N06L3 G	Issued	30. April 2021
MA#	MA002510246		
Package	PG-TO252-3-11	Weight*	373.93 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.152	1.38	1.38	13778	13778
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		173	
	non noble metal	iron	7439-89-6	0.215	0.06		576	
	non noble metal	copper	7440-50-8	215.017	57.50	57.58	575021	575770
wire	non noble metal	aluminium	7429-90-5	6.064	1.62	1.62	16218	16218
encapsulation	inorganic material	zinc oxide	1314-13-2	1.204	0.32		3219	
	miscellaneous	miscellaneous	-	6.019	1.61		16097	
	plastics	epoxy resin	-	18.058	4.83		48292	
	inorganic material	silicon dioxide	60676-86-0	95.105	25.43	32.19	254340	321948
lead finish	non noble metal	tin	7440-31-5	3.740	1.00	1.00	10002	10002
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	243	244
solder	non noble metal	tin	7440-31-5	0.080	0.02		214	
	noble metal	silver	7440-22-4	0.100	0.03		267	
	non noble metal	lead	7439-92-1	3.817	1.02	1.07	10207	10688
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			15	
	non noble metal	iron	7439-89-6	0.019	0.01		51	
	non noble metal	copper	7440-50-8	19.177	5.13	5.14	51286	51352
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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